Intel Patent Sales –

IAM Lot 16 (Packaging – Contacts)

Lot 16 Description: Lot 16 includes 8 patent assets. The patents in Lot 16 relate to various contacts technologies for IC packaging, including thermocompression bonding techniques and methods of individually reflowing chip interconnects separately. The patents also relate to bulk metallic glass solder material, peripheral surface mount components, and surface mount connectors with pins and vias. [Uploaded 30 January 2017.]

	Patent #	Granted or Pending	Country Code	Title
1.	7040012	Granted	US	METHOD OF ELECTRICALLY AND MECHANICALLY CONNECTING ELECTRONIC DEVICES TO ONE ANOTHER
2.	6867124	Granted	US	INTEGRATED CIRCUIT PACKAGING DESIGN AND METHOD
3.	7628871	Granted	US	BULK METALLIC GLASS SOLDER MATERIAL
4.	101282817	Granted	CN	BULK METALLIC GLASS SOLDER
5.	10-1026316	Granted	KR	BULK METALLIC GLASS SOLDER
6.	I315688	Granted	TW	BULK METALLIC GLASS SOLDER
7.	7875973	Granted	US	PACKAGE SUBSTRATE INCLUDING SURFACE MOUNT COMPONENT MOUNTED ON A PERIPHERAL SURFACE THEREOF AND MICROELECTRONIC PACKAGE INCLUDING SAME
8.	6259039	Granted	US	SURFACE MOUNT CONNECTOR WITH PINS IN VIAS